

MBRB2060CT, MBR2060CT

SWITCHMODE™ Power Rectifiers

TO-220/D²PAK Surface Mount Power Package

These state-of-the-art devices employ the use of the Schottky Barrier principle with a platinum barrier metal.

Features

- Package Designed for Power Surface Mount Applications (D²PAK)
- Center-Tap Configuration (D²PAK)
- Guardring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured – Not Sheared (D²PAK)
- Similar in Size to Industry Standard TO-220 Package
- Pb-Free Packages are Available

Mechanical Characteristics:

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 Grams (Approximately) – D²PAK, 1.9 Grams (Approximately) – TO-220
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds (D²PAK)
- Device Meets MSL1 Requirements (D²PAK)
- ESD Ratings: Machine Model, C (>400 V)
Human Body Model, 3B (>8000 V)

MAXIMUM RATINGS (Per Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	60	V
Average Rectified Forward Current (Rated V_R , $T_C = 110^\circ\text{C}$) Total Device	$I_{F(AV)}$	10 20	A
Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz, $T_C = 100^\circ\text{C}$)	I_{FRM}	20	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	150	A
Peak Repetitive Reverse Surge Current (2.0 μs , 1.0 kHz)	I_{RRM}	0.5	A
Storage Temperature Range	T_{stg}	-65 to +175	°C
Operating Junction Temperature (Note 1)	T_J	-65 to +175	°C
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/ μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

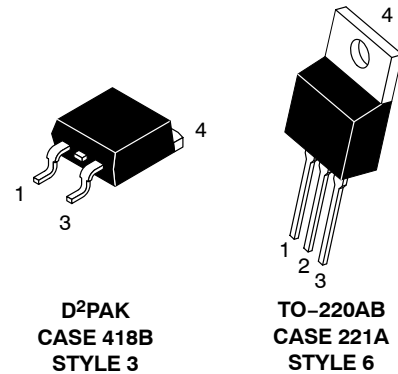
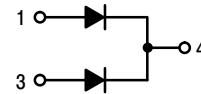
1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.



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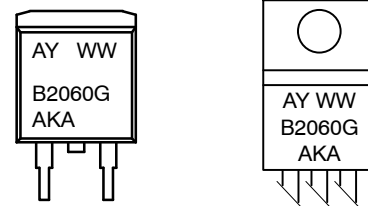
SCHOTTKY BARRIER RECTIFIERS 20 AMPERES, 60 VOLTS



**D²PAK
CASE 418B
STYLE 3**

**TO-220AB
CASE 221A
STYLE 6**

MARKING DIAGRAMS



- A = Assembly Location
- Y = Year
- WW = Work Week
- B2060 = Device Code
- G = Pb-Free Package
- AKA = Diode Polarity

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

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THERMAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Thermal Resistance, - Junction-to-Case	$R_{\theta JC}$	2.0	$^{\circ}\text{C/W}$
- Junction-to-Ambient (Note 2)	$R_{\theta JA}$	50	
- Junction-to-Ambient (Note 2)	$R_{\theta JA}$	60	

2. When mounted using minimum recommended pad size on FR-4 board.

ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) ($i_F = 20$ Amps, $T_J = 125^{\circ}\text{C}$) ($i_F = 20$ Amps, $T_J = 25^{\circ}\text{C}$)	V_F	0.85 0.95	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J = 125^{\circ}\text{C}$) (Rated dc Voltage, $T_J = 25^{\circ}\text{C}$)	i_R	35 0.15	mA

3. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRB2060CT	D ² PAK	50 Units / Rail
MBRB2060CTG	D ² PAK (Pb-Free)	50 Units / Rail
MBRB2060CTT4	D ² PAK	800 Units / Tape & Reel
MBRB2060CTT4G	D ² PAK (Pb-Free)	800 Units / Tape & Reel
MBR2060CT	TO-220	50 Units / Rail
MBR2060CTG	TO-220 (Pb-Free)	50 Units / Rail

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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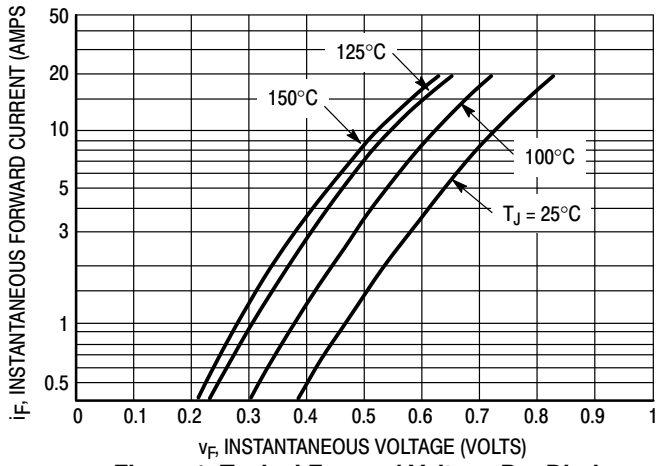


Figure 1. Typical Forward Voltage Per Diode

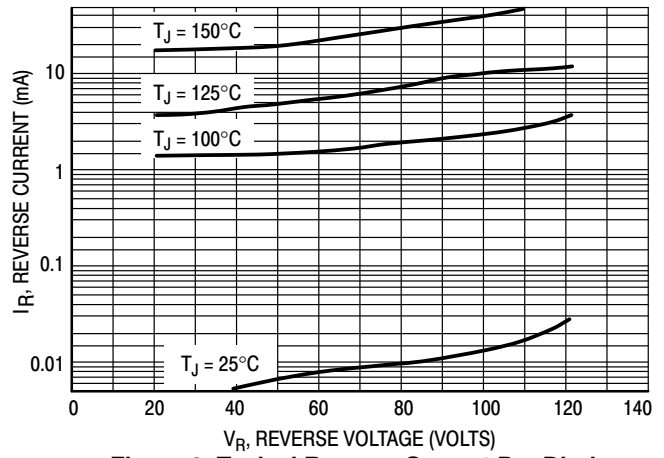


Figure 2. Typical Reverse Current Per Diode

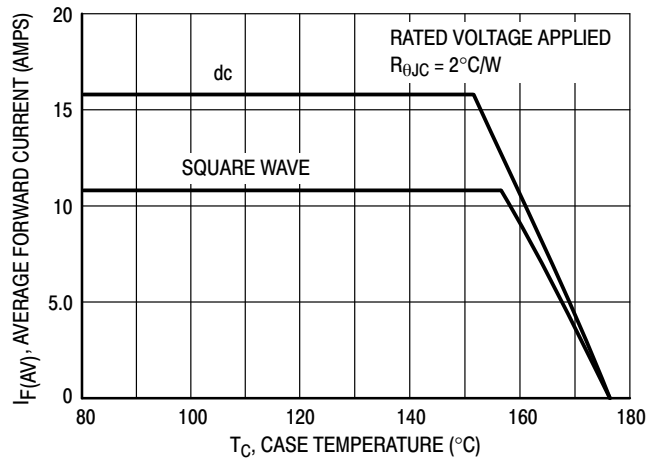


Figure 3. Typical Current Derating, Case, Per Leg

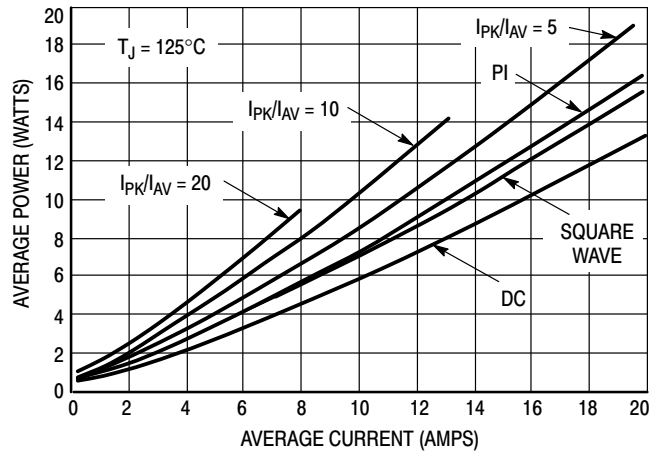
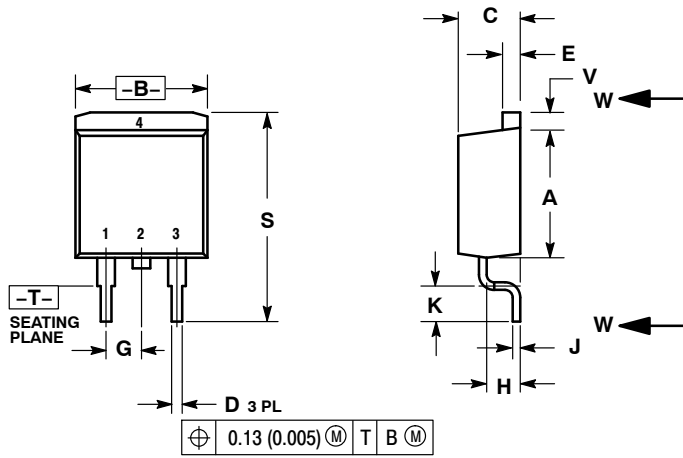


Figure 4. Average Power Dissipation and Average Current

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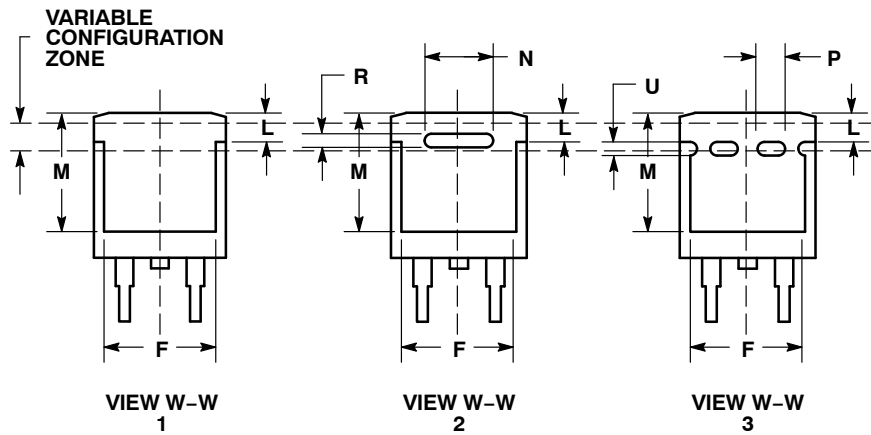
PACKAGE DIMENSIONS

D²PAK 3
CASE 418B-04
ISSUE J



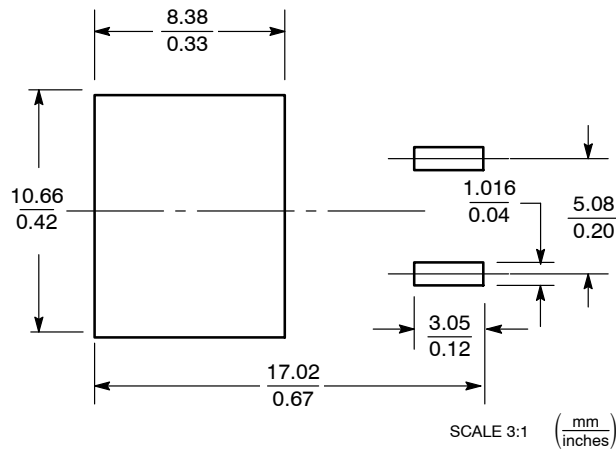
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100	BSC	2.54	BSC
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197	REF	5.00	REF
P	0.079	REF	2.00	REF
R	0.039	REF	0.99	REF
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



- STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

SOLDERING FOOTPRINT*

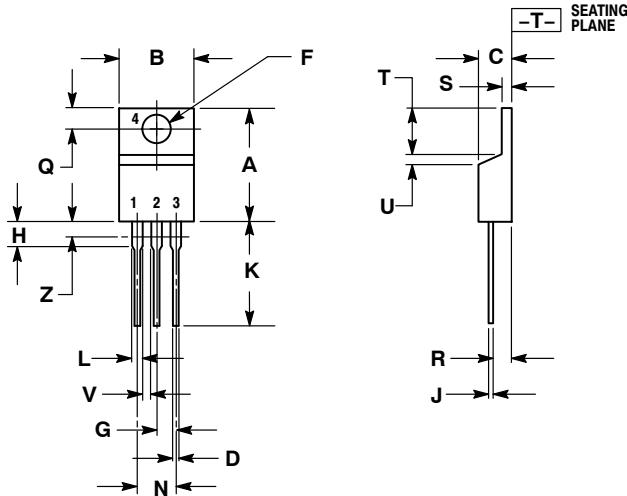


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

TO-220
CASE 221A-09
ISSUE AF



NOTES:


1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

STYLE 6:

1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

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